

AMPLIMITE | AMPLIMITE 0.50 Series

TE Internal #: 5787170-7

PCB D-Sub Connectors, Receptacle, Cable-to-Board, 68 Position,

1.27 mm [.05 in] Centerline, 2 Row, Standard Profile, AMPLIMITE

0.50 Series

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Connectors > D-Shaped Connectors > D-Sub Connectors > PCB D-Sub Connectors > D-Sub Receptacle Assembly: Right Angle, 1.27mm











Connector & Housing Type: Receptacle

Connector System: Cable-to-Board

Number of Positions: 68

Centerline (Pitch): 1.27 mm [.05 in]

Number of Rows: 2

All D-Sub Receptacle Assembly: Right Angle, 1.27mm (76)

Features

Product Type Features

| Froduct Type realures | |
|-----------------------------------|-----------------------|
| Grounding Indents | Without |
| Shell Type | Full Metal Shell |
| Connector & Housing Type | Receptacle |
| Connector System | Cable-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Shielded | Yes |
| Connector Type | Connector Assembly |
| Product Type | Connector |
| Configuration Features | |
| Number of Positions | 68 |

2

Right Angle

Number of Rows

PCB Mount Orientation



| ody Features | |
|---|--|
| Bracket Material | Zinc |
| Shell Plating Finish | Bright |
| Bracket Plating Material | Nickel over Copper |
| Post Plating Material | Tin over Nickel |
| Connector Profile | Standard |
| Shell Plating Material | Nickel over Copper |
| Shell Material | Carbon Steel |
| | .012 in |
| Contact Features | |
| Contact Mating Area Plating Material | Gold, Gold Flash over Palladium Nickel |
| Contact Underplating Material | Palladium Nickel |
| PCB Contact Termination Area Plating Material | Tin-Lead |
| Contact Base Material | Phosphor Bronze |
| Contact Current Rating (Max) | 1 A |
| | 30 µin |
| ermination Features | |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Termination Post Length | 2.54 mm[.1 in] |
| Mechanical Attachment | |
| PCB Mount Alignment | Without |
| PCB Mount Retention | With |
| PCB Mount Retention Type | Boardlock |
| Mating Retention | Without |
| Connector Mounting Type | Board Mount |
| Boardlock Plating Material | Tin over Nickel |
| Boardlock Material | Copper Alloy |
| Mating Alignment | Without |
| | .109 in |
| lousing Features | |
| Centerline (Pitch) | 1.27 mm[.05 in] |
| Housing Material | Thermoplastic |
| | |



| Housing Color | Black |
|-----------------------------|----------------------------|
| Dimensions | |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| PCB Thickness (Recommended) | 1.57 mm[.062 in] |
| Usage Conditions | |
| Operating Temperature Range | -55 – 105 °C[-67 – 221 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| Approved Standards | UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Method | Tube |
| Packaging Quantity | 8 |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts









Also in the Series | AMPLIMITE 0.50 Series



D-Sub Backshells & Clamps(31)



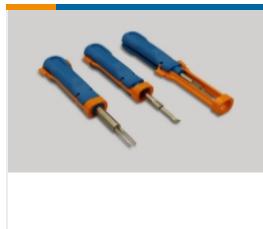
D-Sub Covers(20)



D-Sub Locking & Mounting(8)



IDC D-Sub Connectors(76)



Insertion & Extraction Tools(1)



Documents

Product Drawings

68 50SR R/A RCPT ASSY,RDSN L/F

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5787170-7_A.2d_dxf.zip

English

Customer View Model



ENG_CVM_CVM_5787170-7_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5787170-7_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

AMPLIMITE Subminiature D Connectors - .050 Series Connector

English

AMPLIMITE .050 Series D-sub Connectors QRG

English

Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

English

Agency Approvals

UL

English